Information & Control NA TC Chapter

Meeting Summary and Minutes

Winter Meetings

Wednesday, February 26, 2025

9:00-12:00, 1:00-4:00 PM Pacific Time

SEMI HQ, Milpitas

TC Chapter Announcements

Next TC Chapter Meeting

Wednesday, June 4, 2025

9:00-12:00, 1:00-4:00 PM Pacific Time

SEMI HQ, Milpitas

Table 1 Meeting Attendees

Italics indicate virtual participants

Co-Chairs: James Moyne (Applied Materials / University of Michigan), Brian Rubow (Cimetrix), Albert Fuchigami (PEER Group)
SEMI Staff: Michelle Sun

Company	*Last*	*First*	*Company*	*Last*	*First*
Intertek	*Thomas*	*Nicholas*	Intel	*Bond*	*Ryan*
PDF Solutions	*Weber*	*Alan*	Self	*Howard*	*Richard*
Schneider Electric	March	Stephen	SEMI	Sun	Michelle
Intel	*Maloney*	*Chris*	Hitachi	*Toyoshima*	*Yuko*
Arlington Laboratory	*Judd*	*Daniel*	AMAT/University of Michigan	*Moyne*	*James*
The PEER Group	Albert	Fuchigami			

Table 2 Leadership Changes

WG/TF/SC/TC Name	*Previous Leader*	*New Leader*
EDP Task Force	Shuba Viswanath (Intel) [*stepped down*]	

Table 3 TC Chapter Structure Changes

Previous WG/TF/SC Name	*New WG/TF/SC Name or Status Change*
None	

Table 4 Ballot Results

Document #	*Document Title*	*Committee Action*
7240B	Revision to SEMI E157-0324, Specification for Module Process Tracking, with title change to: Specification for Module and Substrate Process Tracking	**Passed**, Ratification Ballot to be issued

Table 4 Ballot Results

Document #	*Document Title*	*Committee Action*
7311	Line Item Revision to SEMI E191-1024 - Specification for Computing Device Cybersecurity Status Reporting and SEMI E191.1-1024 - Specification for SECS-II Protocol for Computing Device Cybersecurity Status Reporting	
LI-1	Add additional requirements and clarifications to operating system details to be reported	**Failed**
LI-2	Address issues raised by TF members	**Failed**
7312	Line Item Revision to SEMI E5-0224 - Specification for SEMI Equipment Communications Standard 2 Message Content (SECS-II), and SEMI E30-1024 - Specification for the Generic Model for Communications and Control of Manufacturing Equipment (GEM)	
LI-1	Add Well-Known Names to SEMI E5 items and update Well-Known Names in SEMI E30 to match	**Passed**
LI-2	Address issues raised by Task Force Members	**Passed**
7316	Revision to SEMI E90-1224 – Specification for Substrate Tracking and SEMI E90.1-1224- Specification for SECS-II Protocol Substrate Tracking	**Passed**
7321	Line Item Revision to SEMI E120-0922 (Reapproved 1224) Specification for the Common Equipment Model (CEM), SEMI E120.2-1224 Specification for Protocol Buffers for Common Equipment Model (CEM), SEMI E125-1224 Specification for Equipment Self Description (EqSD), SEMI E125.2-1224 Specification for Protocol Buffers for Equipment Self Description (EqSD), SEMI E132-0624 Specification for Equipment Client Authentication and Authorization, SEMI E132.2-1224 Specification for Protocol Buffers for Equipment Client Authentication And Authorization (ECA), SEMI E134-1224 Specification for Data Collection Management, SEMI E134.2-1224 Specification for Protocol Buffers of Data Collection Management, and SEMI E179-1224 Specification for Protocol Buffers Common Components	
LI-1	Provide way to handle data collection errors in cached data reports	**Passed**
LI-2	Update issues raised by TF members	**Failed**

#1 **Passed** ballots and line items will be submitted to the ISC Audit & Review Subcommittee for procedural review.

#2 **Failed** ballots and line items were returned to the originating task forces for re-work and re-balloting or abandoning.

Table 5 Ratification Ballot Results

Document #	*Document Title*	*ISC A&R Action*	*A&R Forms*
None			

Note 1: **Passed** Ratification ballots will be submitted to SEMI publication for final processing.

Note 2: **Failed** Ratification ballots were returned to the originating task forces for re-work and re-balloting or abandoning.

Table 6 Activities Approved by the GCS between meetings of the TC Chapter

#	*Type*	*SC/TF/WG*	*Details*
7321	Ballot Authorization	DDA	Line Item Revision to SEMI E120-0922 (Reapproved 1224) Specification for the Common Equipment Model (CEM), SEMI E120.2-1224 Specification for Protocol Buffers for Common Equipment Model (CEM), SEMI E125-1224 Specification for Equipment Self Description (EqSD), SEMI E125.2-1224 Specification for Protocol Buffers for Equipment Self Description (EqSD), SEMI E132-0624 Specification for Equipment Client Authentication and Authorization, SEMI E132.2-1224 Specification for Protocol Buffers for Equipment Client Authentication And Authorization (ECA), SEMI E134-1224 Specification for Data Collection Management, SEMI E134.2-1224 Specification for Protocol Buffers of Data Collection Management, and SEMI E179-1224 Specification for Protocol Buffers Common Components

Table 7 Authorized Activities

Listing of all revised or new SNARF(s) approved by the Originating TC Chapter.

#	*Type*	*SC/TF/WG*	*Details*
7344	SNARF Approval	GEM300	Line Item Revision to SEMI E192-0125 - Guide for Equipment Adoption Criteria for GEM and GEM-related Standards
7345	SNARF Approval	GEM300	Line Item Revision to SEMI E90-1224, Specification for Substrate Tracking and SEMI E90.1-1224, Specification for SECS-II Protocol Substrate Tracking
7355	SNARF Approval	Sensor Bus TF	Reapproval of SEMI E54.22 (Reapproved 0420) - Specification for Sensor/Actuator Network Specific Device Model for Vacuum Pressure Gauges

#1 SNARFs and TFOFs are available for review on the SEMI Web site at:

http://downloads.semi.org/web/wstdsbal.nsf/TFOFSNARF

Table 8 Authorized Ballots

#	*When*	*TF*	*Details*
6743C	Cycle 3, 4, 5-2025	GUI	Revision to SEMI E95-1101, Specification for Human Interface for Semiconductor Manufacturing Equipment
6926	Cycle 3, 4, 5-2025	CDS	New Standard: Specification for Equipment Operator Access Management and Monitoring
7178	Cycle 3, 4, 5-2025	DDA	Revision to SEMI E164-0414 (Reapproved 0721), Specification for EDA Common Metadata

Table 8 Authorized Ballots

#	*When*	*TF*	*Details*
7179	Cycle 3, 4, 5-2025	DDA	Revision to Add a New Subordinate Standard: Specification for EDA Common Metadata for Generic Model for Communication and Control of Manufacturing Equipment (GEM) to SEMI E164-0414 (Reapproved 0721), Specification for EDA Common Metadata
7180	Cycle 3, 4, 5-2025	DDA	Revision to Add a New Subordinate Standard: Specification for EDA Common Metadata for Processing Management to SEMI E164-0414 (Reapproved 0721), Specification for EDA Common Metadata
7311A	Cycle 3, 4, 5-2025	CDS	Line Item Revision to SEMI E191-1024 - Specification for Computing Device Cybersecurity Status Reporting and SEMI E191.1-1024 - Specification for SECS-II Protocol for Computing Device Cybersecurity Status Reporting
7270	Cycle 3, 4, 5-2025	GEM 300	Line Item Revision to SEMI E151-1211 (Reapproved 0517), Guide for Understanding Data Quality
7321A	Cycle 3, 4, 5-2025	DDA	Line Item Revision to SEMI E120-0922 (Reapproved 1224) Specification for the Common Equipment Model (CEM), SEMI E120.2-1224 Specification for Protocol Buffers for Common Equipment Model (CEM), SEMI E125-1224, Specification for Equipment Self Description (EqSD), SEMI E125.2-1224, Specification for Protocol Buffers for Equipment Self Description (EqSD), SEMI E132-0624, Specification for Equipment Client Authentication and Authorization, SEMI E132.2-1224, Specification for Protocol Buffers for Equipment Client Authentication And Authorization (ECA), SEMI E134-1224, Specification for Data Collection Management, SEMI E134.2-1224, Specification for Protocol Buffers of Data Collection Management, and SEMI E179-1224, Specification for Protocol Buffers Common Components
7187	Cycle 3, 4, 5-2025	ESEC	Revision to SEMI E167-1213 - Specification for Equipment Energy Saving Mode Communications (EESM) and SEMI E167.1-1213 - Specification for SECS-II Protocol for Equipment Energy Saving Mode Communications
7344	Cycle 3, 4, 5-2025	GEM300	Line Item Revision to SEMI E192-0125 - Guide for Equipment Adoption Criteria for GEM and GEM-related Standards
7345	Cycle 3, 4, 5-2025	GEM300	Line Item Revision to SEMI E90-1224, Specification for Substrate Tracking and SEMI E90.1-1224, Specification for SECS-II Protocol Substrate Tracking
7346	Cycle 3, 4, 5-2025	Sensor Bus TF	Line Item Revision to SEMI E54.23-0520, Specification for Sensor/Actuator Network Communications for CC-LINK® IE
7347	Cycle 3, 4, 5-2025	Sensor Bus	Reapproval of SEMI E54.18-0914 (Reapproved 0420) - Specification for Sensor/Actuator Network Specific Device Model for Vacuum Pump Device
7348	Cycle 3, 4, 5-2025	Sensor Bus	Reapproval of SEMI E54.23-0520 - Specification for Sensor/Actuator Network Communications for CC-LINK® IE

Table 9 SNARF(s) Granted a One-Year Extension

#	*TF*	*Title*	*Expiration Date*
6923	ESEC	Line Item Revisions to SEMI E167-1213: Specification for Equipment Energy Saving Mode Communications (EESM), SEMI E167.1-1213: Specification for SECS-II Protocol for Equipment Energy Saving Mode Communications, and SEMI E175-1116: Specification for Subsystem Energy Saving Mode Communication (SESMC)	2/26/2026
6926	CDS	New Standard: Specification for Equipment Operator Access Management and Monitoring	2/26/2026

Table 10 SNARF(s) Cancelled

#	TF	Title
6992	GEM300	Line Item Revision to SEMI E157-0611 (Reapproved 0616), Specification for Module Process Tracking

Table 11 Standard(s) to receive Inactive Status

Standard Designation	Title
None	

Table 12 New Action Items

Item #	Assigned to	Details
None		

Table 13 Previous Meeting Action Items

Item #	Assigned to	Details
None		

1 Welcome, Reminders, and Introductions

Brian Rubow (Cimetrix) called the meeting to order at 9:05. The meeting reminders on antitrust issues, intellectual property issues and holding meetings with international attendance were reviewed. Attendees introduced themselves.

Attachment: Required Meeting Elements March 2024

2 Review of Previous Meeting Minutes

The TC Chapter reviewed the minutes of the previous meeting.

Motion:	Approve the minutes as written
By / 2nd:	By: Takayuki Nishimura / SCREEN Semiconductor Solutions Co., Ltd. Second: Brian Rubow / Cimetrix Incorporated
Discussion:	None
Vote:	11-Y 0-N

Attachment: IC-Minutes-Feb-2025

3 Liaison Reports

3.1 *I&C Taiwan TC Chapter*

Michelle Sun (SEMI) reported for the Information & Control Taiwan TC Chapter. Of note:

- Last meeting
  - November 29, 2024
- Next meeting
  - TBD
- Organization Chart
  - Equipment Information Integration TF, GEM300 TF, Backend Factory Integration TF disbanded

- Authorized Activities
    - Major Revision of E187 - Specification for Cybersecurity of Fab Equipment

Attachment: IC Taiwan Liaison Report_20241129_V1

3.2 *I&C Japan TC Chapter*

Takayuki Nishimura (SCREEN) reported for the I&C Japan TC Chapter. Of note:

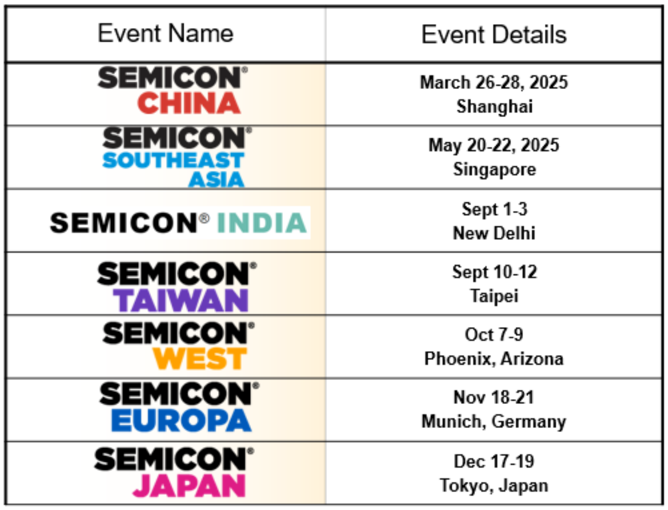
- Last meeting
    - Friday December 13th, 2024, 13:30-16:30 [JST]
    - International Conference Hall, SEMICON Japan 2024 + OVTCCM [Hybrid]
- Next meeting
    - Friday April 18th, 2025, 13:30-16:30 [JST]
    - SEMI Japan Office + OVTCCM [Hybrid]
- Ballot Results
    - 7005, Line Item Revision to SEMI E91-1217: SPECIFICATION FOR PROBER SPECIFIC EQUIPMENT MODEL (PSEM) **[JST]**
    - R7173, Line-Item Revision to SEMI E30-0224, Specification for the Generic Model for Communications and Control of Manufacturing Equipment (GEM) **[JST]**
- Authorized Ballots
    - 7334, Line Item Revision to SEMI E174-0819 SPECIFICATION FOR WAFER JOB MANAGEMENT (WJM)
    - 7330, Line Item Revision to SEMI E178-0120 GUIDE FOR EDA FREEZE VERSION

Attachment: JA_I&C_Liaison_2025_Feb_Ver2

3.3 *SEMI Staff Report*

Michelle Sun (SEMI) gave the SEMI Staff Report. Of note:

2025 Calendar of Events



Event Name	Event Details
SEMICON® CHINA	March 26-28, 2025 Shanghai
SEMICON® SOUTHEAST ASIA	May 20-22, 2025 Singapore
SEMICON® INDIA	Sept 1-3 New Delhi
SEMICON® TAIWAN	Sept 10-12 Taipei
SEMICON® WEST	Oct 7-9 Phoenix, Arizona
SEMICON® EUROPA	Nov 18-21 Munich, Germany
SEMICON® JAPAN	Dec 17-19 Tokyo, Japan

SEMICON West 2025-2030

- **2025—October 7-9 | Phoenix Convention Center | Phoenix, AZ**
- 2026—October 13-15 | Moscone Center | San Francisco, CA
- **2027—October 12-14 | Phoenix Convention Center | Phoenix, AZ**
- 2028—October 10-12 | Moscone Center | San Francisco, CA
- **2029—October 9-11 | Phoenix Convention Center | Phoenix, AZ**

- 2030—October 29-31 | Moscone Center | San Francisco, CA

Upcoming NA Meetings 2025

Event Name	Date/Venue	Ballot Cycles to Consider
NA Standards Meetings	June 2-5, 2025 SEMI HQ, Milpitas, California/USA	**Cycle 3-25** Ballot Submission Date: Wednesday, March 5, 2025 Voting Period Starts: Wednesday, March 19, 2025 Voting Period Ends: Friday, April 18, 2025 **Cycle 4-25** Ballot Submission Date: Thursday, March 20, 2025 Voting Period Starts: Wednesday, April 9, 2025 Voting Period Ends: Friday, May 9, 2025
SEMICON West	Oct 7-9, 2025 Phoenix Convention Center Phoenix, Arizona/USA	**Cycle 6-25** Ballot Submission Date: Thursday, June 19, 2025 Voting Period Starts: Wednesday, July 9, 2025 Voting Period Ends: Friday, August 8, 2025 **Cycle 7-25** Ballot Submission Date: Thursday, July 24, 2025 Voting Period Starts: Wednesday, August 13, 2025 Voting Period Ends: Friday, September 12, 2025

Critical Dates for SEMI Standards Ballots – 2025

2025	Ballot Submission Deadline	Voting Opens	Voting Closes
Cycle 2	January 23	February 11	March 13
Cycle 3	March 5	March 19	April 18
Cycle 4	March 20	April 9	May 9
Cycle 5	May 8	May 28	June 27
Cycle 6	June 19	July 9	August 8
Cycle 7	July 24	August 13	September 12

SEMI Standards Publications

- Total SEMI Standards in portfolio: 1,098
  - Includes 356 Inactive Standards

Regulations & Procedure Manual Updates

- Regulations (Feb 20, 2024)
  - New definition of "Standards Document"
  - Clarification of confidential presentation materials
    - https://www.semi.org/sites/semi.org/files/2024-02/Standards%20Regulations%20February%2020%202024.pdf
- Procedure Manual (Sept 27, 2024)
  - Clarification of § 6.4.5.10 for discharging of a TF

  - New ¶ 6.4.5.11 Designation of a TF as Dormant.
    - https://www.semi.org/sites/semi.org/files/2024-09/Procedure%20Manual%20September%2027%2C%202024.pdf

Connect@SEMI Communities for all SEMI Standards Task Forces [1/5]

- By Feb 2025, all Standards Task Forces shall use Connect@SEMI to host documents that are currently in development.
- Each Standards Task Force will have its own Community Page on Connect@SEMI.
- All Program Members may log in at:
  - https://connect.semi.org
  - Enter their username and password (same as program membership log-in)

SNARF 3-Year Status

Date	**Doc**	**Description**
12/08/2021	6894	Line Item Revision to E33-0217E, Guide for Semiconductor Manufacturing Equipment Electromagnetic Compatibility (EMC) and E176-1017, Guide to Assess and Minimize Electromagnetic Interference (EMI) in a Semiconductor Manufacturing Environment
12/06/2021	6971	Revision to SEMI E163-0212, Guide for the Handling of Reticles and Other Extremely Electrostatic Sensitive (EES) Items Within Specially Designated Areas

Attachment: IC-Staff Report Feb 2025 v2

4 Ballot Review

NOTE 1: TC Chapter adjudication on ballots reviewed is detailed in the Audits & Review (A&R) Subcommittee Forms for procedural review. The A&R forms are available as attachments to these minutes. The attachment number for each balloted document is provided under each ballot review section below.

4.1 Document #7240B, Revision to SEMI E157-0324, Specification for Module Process Tracking, with title change to: Specification for Module and Substrate Process Tracking

Motion:	This Document passed TC Chapter review with technical changes and with or without editorial changes and will be forwarded to the ISC A&R SC for procedural review. A Ratification Ballot will be issued to verify the technical changes.
By / 2nd:	By: Takayuki Nishimura / SCREEN Semiconductor Solutions Co., Ltd. Second: Tami Tracey / Cimetrix Incorporated
Discussion:	None
Vote:	7-Y 0-N

Attachment: AR - 7240B v2

4.2 Document #7312, Line Item Revision to SEMI E5-0224 - Specification for SEMI Equipment Communications Standard 2 Message Content (SECS-II), and SEMI E30-1024 - Specification for the Generic Model for Communications and Control of Manufacturing Equipment (GEM)

Motion:	Line item(s) [1], [2] passed TC Chapter review as balloted and will be forwarded to the ISC A&R SC for procedural review.
By / 2nd:	By: Albert Fuchigami / PEER Group Inc. Second: Brian Rubow / Cimetrix Incorporated
Discussion:	None
Vote:	10-Y 0-N

Attachment: AR - 7312

4.3 Document #7311, Line Item Revision to SEMI E191-1024 - Specification for Computing Device Cybersecurity Status Reporting and SEMI E191.1-1024 - Specification for SECS-II Protocol for Computing Device Cybersecurity Status Reporting

Motion:	This Document failed TC Chapter review and will be returned to the TF for rework
By / 2nd:	By: Albert Fuchigami / PEER Group Inc. Second: Richard Howard
Discussion:	None
Vote:	9-Y 0-N

4.4 Document #7316, Revision to SEMI E90-1224 – Specification for Substrate Tracking and SEMI E90.1-1224-Specification for SECS-II Protocol Substrate Tracking

Motion:	This Document passed TC Chapter review as balloted and will be forwarded to the ISC A&R SC for procedural review
By / 2nd:	By: Brian Rubow / Cimetrix Incorporated Second: Stephen March / SE
Discussion:	None
Vote:	10-Y 0-N

Attachment: AR - 7316

4.5 Document #7321, Line Item Revision to SEMI E120-0922 (Reapproved 1224) Specification for the Common Equipment Model (CEM), SEMI E120.2-1224 Specification for Protocol Buffers for Common Equipment Model (CEM), SEMI E125-1224 Specification for Equipment Self Description (EqSD), SEMI E125.2-1224 Specification for Protocol Buffers for Equipment Self Description (EqSD), SEMI E132-0624 Specification for Equipment Client Authentication and Authorization, SEMI E132.2-1224 Specification for Protocol Buffers for Equipment Client Authentication And Authorization (ECA), SEMI E134-1224 Specification for Data Collection Management, SEMI E134.2-1224 Specification for Protocol Buffers of Data Collection Management, and SEMI E179-1224 Specification for Protocol Buffers Common Components

Motion:	Line item(s) [1] passed TC Chapter review as balloted and will be forwarded to the ISC A&R SC for procedural review Line item(s) [2] failed TC Chapter review and will be returned to the TF for rework
By / 2nd:	By: Brian Rubow / Cimetrix Incorporated Second: Stephen March / SE
Discussion:	None
Vote:	11-Y 0-N

Attachment: AR - 7321

5 Subcommittee and Task Force Reports

5.1 *ABFI Task Force*

Brian Rubow (PDF Solutions) reported for the ABFI Task Force. Of note:

- SEMI E192
    - SEMI E192 is now published.

    - SEMI E192 is a guide for all GEM related standards. Therefore, the standard should be updated when new GEM-related standards are created and when the scope changes for an existing GEM-related standard.
- SEMI E90
    - Currently, E90 only supports single substrate id reader availability
    - In some equipment multiple substrate id readers are required due to following reasons
        - Different substrate types (Wafer, Strip, Tray, Panel, TnR, PCB) require different id readers
        - Different material flow of same substrate type would require multiple substrate id readers
        - Substrate may have frontside and backside id, e.g., two bonded wafers
- SEMI E142
    - Use Cases
        - Inspection may be performed on un-patterned wafers.
        - Defect wafer XY coordinates (microns) should be mapped to E142 PhysicalCoordinates
        - Test cells (tester and prober) use their own wafer origin orientation, etc.
        - Device wafer XY coordinates (col, row) should be mapped to E142 LogicalCoordinates
        - Assembly and final test equipment that support mapping should follow E142 SEMI standard
    - Proposal
        - New SNARF for E142 wafer XY mapping table / algorithm
    - Action
        - Liaison with RITdb TF (next meeting Feb 27th) – Albert, John
        - Prepare SNARF for E142 wafer XY mapping table / algorithm – Dave

Attachment: ABFI TF Meeting_022425

5.2 *CDS Task Force*

Other Operating System Details to report

Current/Proposed

- OS Details – Computing Device identifier, OS Manufacturer, OS Name, OS Version, OS Build
- OS Installed Updates – OS Updates installed on the computing device
- OS Installed Components – OS components installed on the computing device

Future:

- Factory Network connection details? IP Address (IPv4, IPv6), DNS, HostName, MAC Address
- USB Accessibility? OS details reporting if USB devices are enabled? (removeable storage, human input device, printers, other?)
- Port Management? Open Ports? Attached services?

Attachment: CDS TF Meeting 20250225_v2

5.3 *DDA Task Force*

EDA Software Vendor Tests

- Test Session #3 held in November 2024. 5 participants (1 equipment supplier, 4 solution providers) Focused on SEMI E134 functionality (defining DCPs and getting NewData messages). Issues being addressed in EDA Standards.
- No additional vendor tests planned – if TF members interested in inter-operability testing, individual sessions can be coordinated)

EDA Standards Update

- Addressing issues found in Test Session #3 and reported by TF Members.

SEMI E164

- Ongoing concentrated ballot development efforts – reworking E164 int into Primary Standard approach, defining only general metadata requirements and defining subordinate standard approach for content standard metadata.
- Planning informational ballot for first subordinate standard (SEMI E40 content) to validate approach and complementary files using JSONC format.

Attachment: DDA TF Report - February 2025_Rev 1.0

5.4 *GUI Task Force*

Tami Tracey (Cimetrix) reported for the GUI Task Force.

TF Meeting Results

- Reviewed 6743C draft revision 3.3
- Items discussed in the meeting
  - User selection (cursor) convention for the document
  - Addition of terms *affordance* and *signifier*
  - Screen Layouts ‘Type 1’ and ‘Type 2’
  - Screen Layouts for SSD – Figure revisions
  - Member suggestion to allow adjacent placement of view-to-view navigation area and navigation panel
  - Proposal to use Informational Ballot process

Attachment: GUI TF Report - 2025-02-25

5.5 *PCS Task Force*

James Moyne (AMAT/University of Michigan) reported for the PCS Task Force.

TF Meeting Results

- **Date and Event**
  - **# of attendees in person: 7 (including staff)**
  - **# of attendees remote/online: 5**
- **TF Leadership & changes (if any): <u>None</u>**
- **New SNARFs: <u>None</u>**
- **Ballot Adjudication: <u>None</u>**
- **New business**
  - **Ballot 7270: Line Item update to SEMI E151-1211, Guide for understanding data quality**
    - Ballot reviewed and will be updated.
  - **SNARF:** NEW STANDARD: Specification for Failure Analysis Reporting
    - Available for review
    - Standard to be developed in the PCS TF
  - **E133 and Digital Twins**
    - Delay in federal funding for Center for Digital Twins has resulted in the delay on the start of this work.

Attachment: PCS-TF-report20250224

5.6 *Sensor Bus Task Force*

Dan Judd (Arlington Laboratory) reported for the Sensor Bus Task Force. Of note:

Ballot Plans

5-Year	**Standard**	**SAN:C for**	**Status**
10/2023	E54.19-1018	Mechatrolink	SNARF Nov 8, 2023 **Dormant**
10/2023	E54.17-1018	A-Link	Editor/Expert not found
10/2024	E54.21-1019	MotionNet	Editor/Expert not found
05/2025	E54.23-0520	CC-Link IE	Editor/Expert identified. Ballot expected Cycle 4 2025.

Attachment: SensorBusTF-SEMINA-Feb-2025-v0.1

5.7 *GEM300 Task Force*

Brian Rubow (Cimetrix) reported for the GEM300 Task Force. Of note:

Meeting Results (Technical Summary)

- Adjudicated Ballots 7312-1, 7312-2, 7316-1, 7240B-1
    - We had several long discussions while adjudicating ballot 7240B-1 (E157).
- Reviewed E90 SNARF
    - There is a contradiction between the state definitions and the transition table regarding the creation and destruction of batches.
    - There is a lack of substrate tracking available to report during batch creation and destruction.
    - Bob, Brian and Albert plan to work on the ballot to propose to the task force
- Ran out of time trying to discuss:
    - collection event/status variable association, which is not reported through the GEM interface right now.
    - Possible timing issues related to E87

Attachment: SEMI NA-ICC-GEM300-TF Report Winter 2025

6 Next Meeting and Adjournment

The next meeting is scheduled for Wednesday, June 4, 2025, from 9:00-12:00, 1:00-4:00 PM Pacific Time at SEMI HQ/Miltpitas. See http://www.semi.org/standards-events for the current list of events.

Adjournment: 2:31.

Respectfully submitted by:

Michelle Sun
Coordinator
SEMI North America
Email: msun@semi.org

Minutes tentatively approved by:

<Name> (<Company>), Co-chair	<Date approved>
<Name> (<Company>), Co-chair	<Date approved>

Table 14 Index of Available Attachments[#1]

Title	*Title*
Required Meeting Elements March 2024	IC-Staff Report Feb 2025 v2
IC-Minutes-Feb-2025	AR - 7240B v2
IC Taiwan Liaison Report_20241129_V1	AR - 7312
JA_I&C_Liaison_2025_Feb_Ver2	AR - 7316
AR - 7321	ABFI TF Meeting_022425
CDS TF Meeting 20250225_v2	DDA TF Report - February 2025_Rev 1.0
GUI TF Report - 2025-02-25	PCS-TF-report20250224
SensorBusTF-SEMINA-Feb-2025-v0.1	SEMI NA-ICC-GEM300-TF Report Winter 2025

#1 Due to file size and delivery issues, attachments must be downloaded separately. A .zip file containing all attachments for these minutes is available at www.semi.org. For additional information or to obtain individual attachments, please contact [SEMI Staff Name] at the contact information above.